

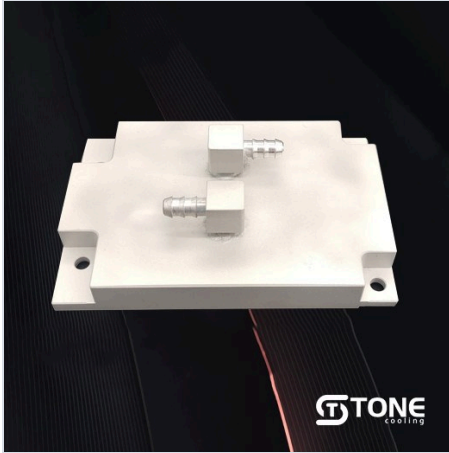
AMD EPYC SP3 CPU Liquid Cold Plate

Model T-HS202318 · AMD CPU · 260 W · Copper, TLP

 Rated heat load
260 W

 Max. surface temp.
<55 °C

 Flow / pressure drop
1 LPM / 3 kPa

 Total height
16 mm


T-HS202318

16 mm slim copper cold plate for AMD EPYC 7002/7003 (SP3, LGA4094). Sized for the 260 W platform limit: surface below 55 °C at 40 °C inlet (15 K rise, ≈ 0.058 °C/W) with just 3 kPa at 1 LPM. The low height clears DIMM latches and 1U lids; the low pressure drop suits retrofit loops running on existing pumps.

Performance & mechanical data

Parameter	Value
Rated heat load	260 W
Coolant (as tested)	25% EG / water (EGW)
Inlet coolant temperature	40 °C
Max. plate surface temperature	< 55 °C
Flow rate / pressure drop	1 LPM / 3 kPa
Working pressure rating	1 MPa
Dimensions (L × W × H)	118 × 92 × 16 mm

 Case-to-inlet thermal resistance: ≈ 0.0577 °C/W (from rated point)

Construction

Parameter	Value
Base material	Copper
Bonding process	TLP – Transient Liquid-Phase Diffusion Bonding
Working pressure rating	1 MPa
Coolant compatibility	Water / EGW / PGW mixtures (validated as listed)
Fittings & port position	Per drawing; customisable on request
Leak test	100% pressure-tested before shipment

Typical applications

- AMD EPYC Rome / Milan servers
- High-density multi-node chassis
- Retrofit of existing SP3 platforms

Ordering & RFQ

How to order: quote model T-HS202318 with quantity and required fitting type.

RFQ checklist: target device / PCB, quantity, coolant type, inlet temperature, target flow rate, mechanical envelope.

Contact: www.tonecooling.com · sales@tonecooling.com

Performance values are typical results at the stated coolant, inlet temperature and flow rate; surface temperature is measured at the device contact area. TIM and mounting pressure affect final junction temperature. Specifications subject to change without notice. Third-party product names are trademarks of their respective owners and are used for compatibility reference only. © 2026 ToneCooling Technology Co., Ltd.